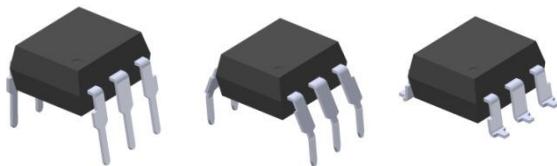
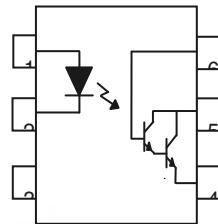


6 PIN DIP PHOTODARLINGTON PHOTOCOUPLED TIL113, 4NXX, H11BX Series

Schematic

Features:

- 4NXX series: 4N29, 4N30, 4N31, 4N32, 4N33
- H11BX series: H11B1, H11B2, H11B3, H11B255
- High isolation voltage between input and output (Viso=5000 V rms)
- Creepage distance >7.62 mm
- Operating temperature up to +110°C
- Compact small outline package
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

Pin Configuration

1. Anode
2. Cathode
3. No Connection
4. Emitter
5. Collector
6. Base

Description

The TIL113, 4NXX and H11BX series of devices each consist of an infrared emitting diode optically coupled to a photo darlington detector.

They are packaged in a 6-pin DIP package and available in wide-lead spacing and SMD option.

Applications

- Low power logic circuits
- Telecommunications equipment
- Portable electronics
- Interfacing coupling systems of different potentials and impedances

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I _F	60	mA
	Peak forward current (1us, pulse)	I _{FP}	1	A
	Reverse voltage	V _R	6	V
	Power dissipation No derating required up to Ta = 100°C	P _D	120 3.8	mW mW/°C
Output	Power dissipation Derating factor (above Ta = 80°C)	P _C	150 6.5	mW mW/°C
	Collector-Emitter voltage	V _{CEO}	55	V
	Collector-Base voltage	V _{CBO}	55	V
	Emitter-Collector voltage	V _{ECO}	7	V
	Emitter-Base voltage	V _{EBO}	7	V
	Total power dissipation	P _{TOT}	200	mW
	Isolation voltage	V _{ISO}	5000	Vrms
	Operating temperature	T _{OPR}	-55~+100	°C
Storage temperature		T _{STG}	-55~+125	°C
Soldering temperature ^{*2}		T _{SOL}	260	°C

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 & 3 are shorted together, and pins 4, 5 & 6 are shorted together.

*2 For 10 seconds

Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Forward Voltage	V _F	-	1.2	1.5	V	I _F = 10mA I _F = 50mA for H11B3
Reverse Current	I _R	-	-	10	µA	V _R = 6V
Input capacitance	C _{in}	-	50	-	pF	V = 0, f = 1MHz

Output

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Collector-Emitter dark current	I _{CEO}	-	-	100	nA	V _{CE} = 10V
Collector-Emitter breakdown voltage	BV _{CEO}	55	-	-	V	I _C = 1mA
Emitter-Collector breakdown voltage	BV _{CBO}	55	-	-	V	I _C = 0.1mA
Emitter-Collector breakdown voltage	BV _{ECO}	7	-	-	V	I _E = 0.1mA

Transfer Characteristics (Ta=25°C unless specified otherwise)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition		
Current transfer ratio	4N32	500	-	-	%	I _F = 10mA, V _{CE} = 10V		
	4N33							
	4N29	100	-	-				
	4N30							
	4N31	50	-	-				
	H11B1							
	CTR	500	-	-				
	H11B2							
	H11B3	100	-	-				
	H11B255							
	TIL113	300	-	-				

Transfer Characteristics ($T_a=25^\circ\text{C}$ unless specified otherwise)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-emitter saturation voltage	4N29					
	4N30	-	-	1.0		$I_F = 8\text{mA}, I_C = 2\text{mA}$
	4N32					
	4N33					
	4N31					
	TIL113	$V_{CE(\text{sat})}$	-	1.2	V	$I_F = 8\text{mA}, I_C = 2\text{mA}$
	H11B1					
	H11B2	-	-	1.0		$I_F = 1\text{mA}, I_C = 1\text{mA}$
	H11B3					
	H11B255	-	-	1.0		$I_F = 50\text{mA}, I_C = 50\text{mA}$
Isolation resistance	R_{IO}	10^{11}	-	-	Ω	$V_{IO} = 500\text{Vdc}$
Input-output Capacitance	C_{IO}	-	0.8	-	pF	$V_{IO} = 0, f = 1\text{MHz}$
Turn-on time	H11B1					
	H11B2	-	25	-		$V_{CC} = 10\text{V}, I_F = 10\text{mA}, R_L = 100\Omega$
	H11B3					
	H11B255					
	4N29	T_{on}			μs	
	4N30		-	5		$V_{CC} = 10\text{V}, I_C = 50\text{mA}, I_F = 200\text{mA}$
	4N31		-			
	4N32		-			
	4N33		-			
	TIL113					
Turn-off time	H11B1					
	H11B2	-	18	-		$V_{CC} = 10\text{V}, I_F = 10\text{mA}, R_L = 100\Omega$
	H11B3					
	H11B255					
	4N32	T_{off}	-	100	μs	
	4N33		-			$V_{CC} = 10\text{V}, I_C = 50\text{mA}, I_F = 200\text{mA}$
	TIL113					
	4N29		-	40		
	4N30					
	4N31					

* Typical values at $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves

Figure 1. Forward Current vs Forward Voltage

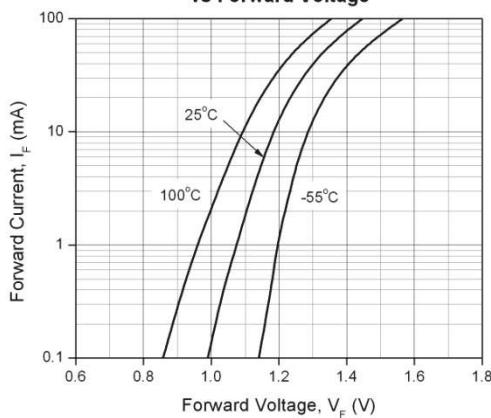


Figure 2. Current Transfer Ratio vs. Ambient Temperature

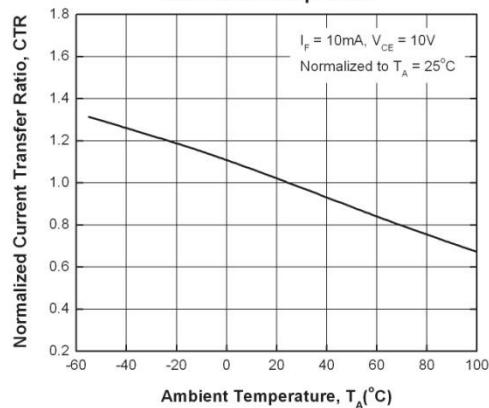


Figure 3. Normalized Current Transfer Ratio vs Forward Current

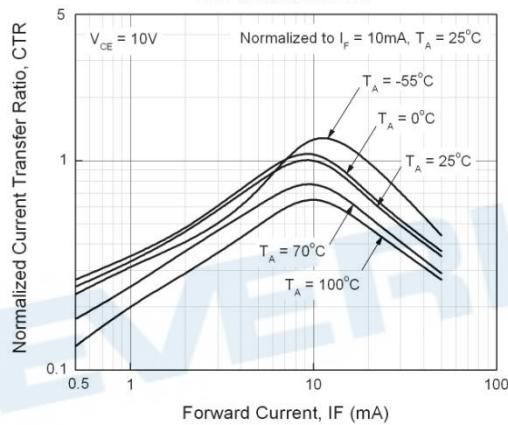


Figure 4. Collector Dark Current vs Ambient Temperature

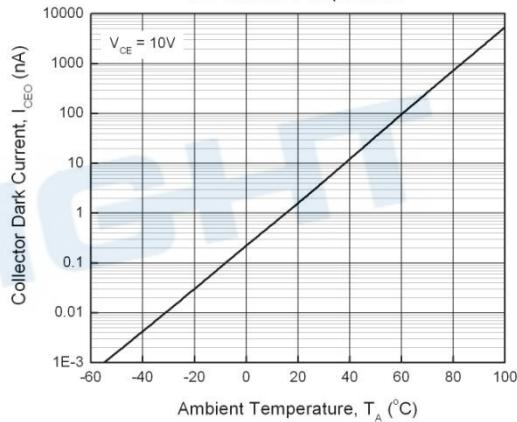


Figure 5. Turn-on Time vs Forward Current

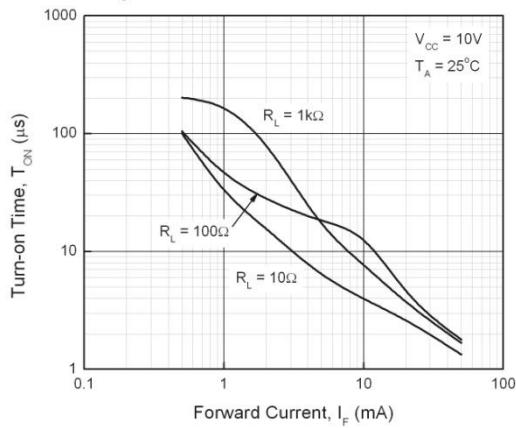
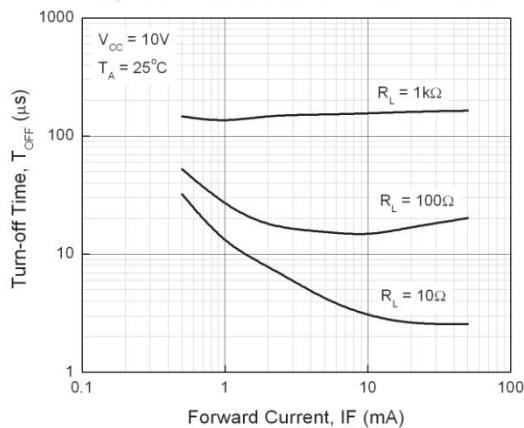


Figure 6. Turn-off Time vs Forward Current



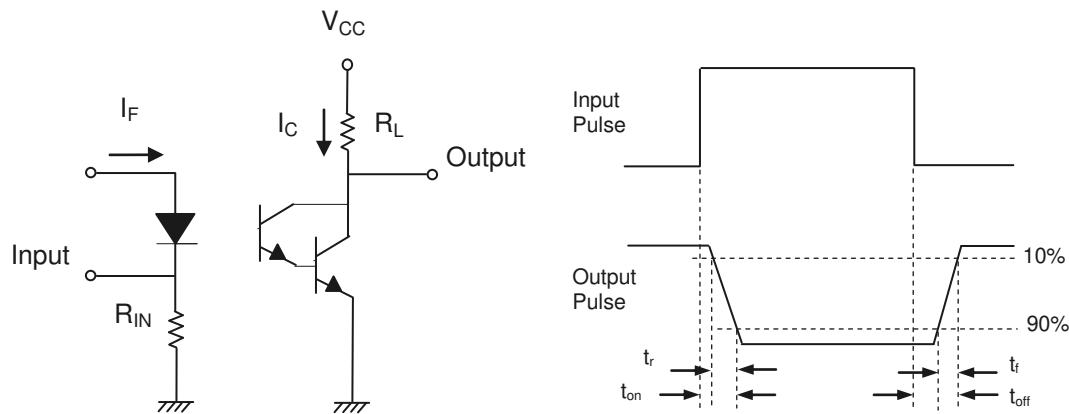


Figure 7. Switching Time Test Circuit & Waveforms

Order Information

Part Number

4NXXY(Z)-V
 or **H11BXY(Z)-V**
 or **TIL113Y(Z)-V**

Note

XX = Part No. for 4NXX series (29, 30, 31, 32 or 33)

X = Part No. for H11BX series (1, 2, 3 or 255)

Y = Lead form option (S, S1, M or none)

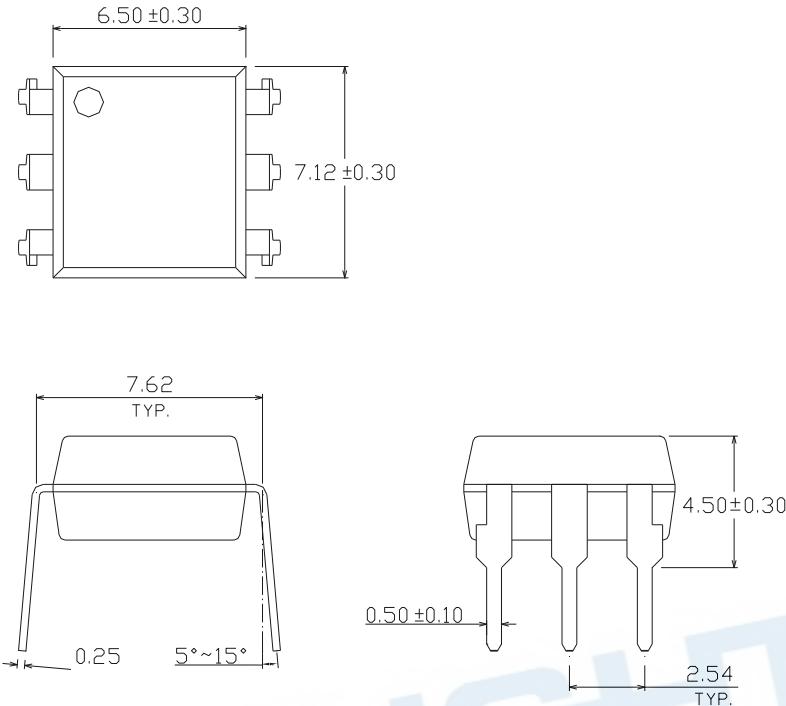
Z = Tape and reel option (TA, TB or none).

V = VDE safety (optional)

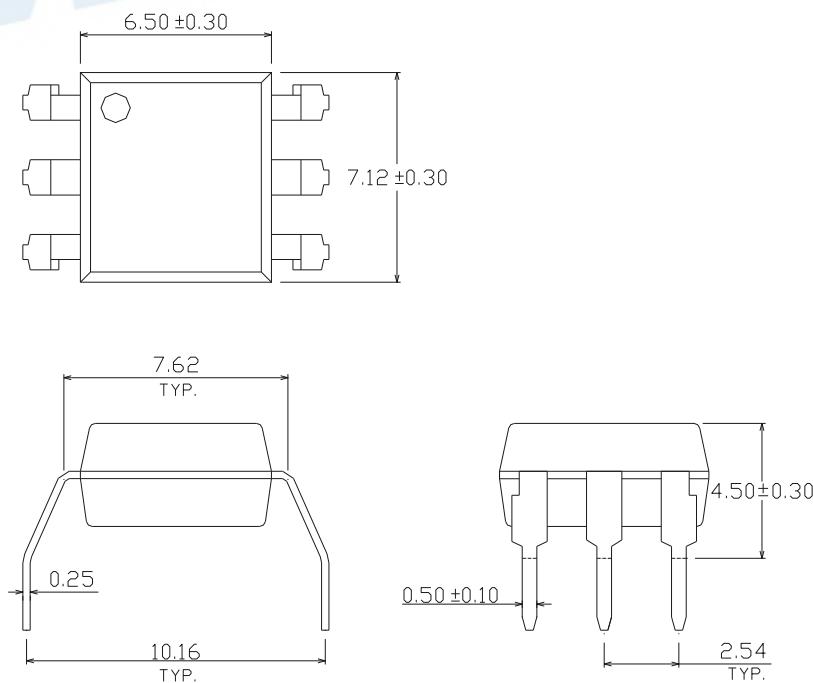
Option	Description	Packing quantity
None	Standard DIP-6	65 units per tube
M	Wide lead bend (0.4 inch spacing)	65 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

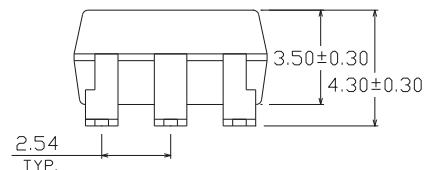
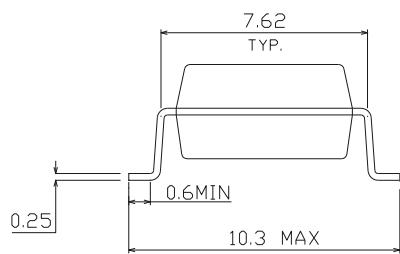
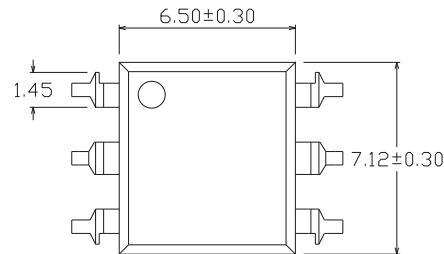
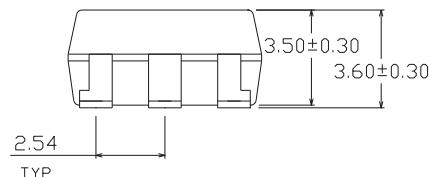
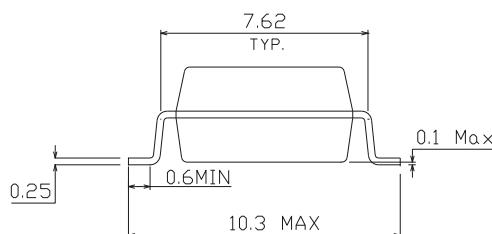
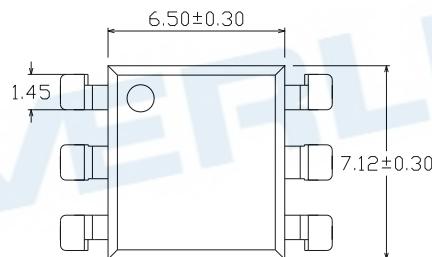
Package Dimension (Dimensions in mm)

Standard DIP Type

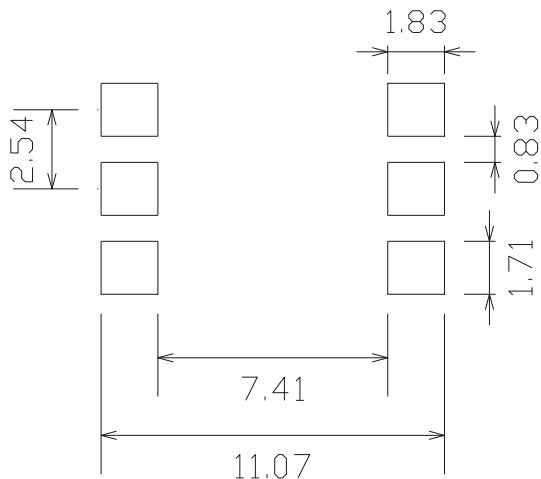


Option M Type



Option S Type**Option S1 Type**

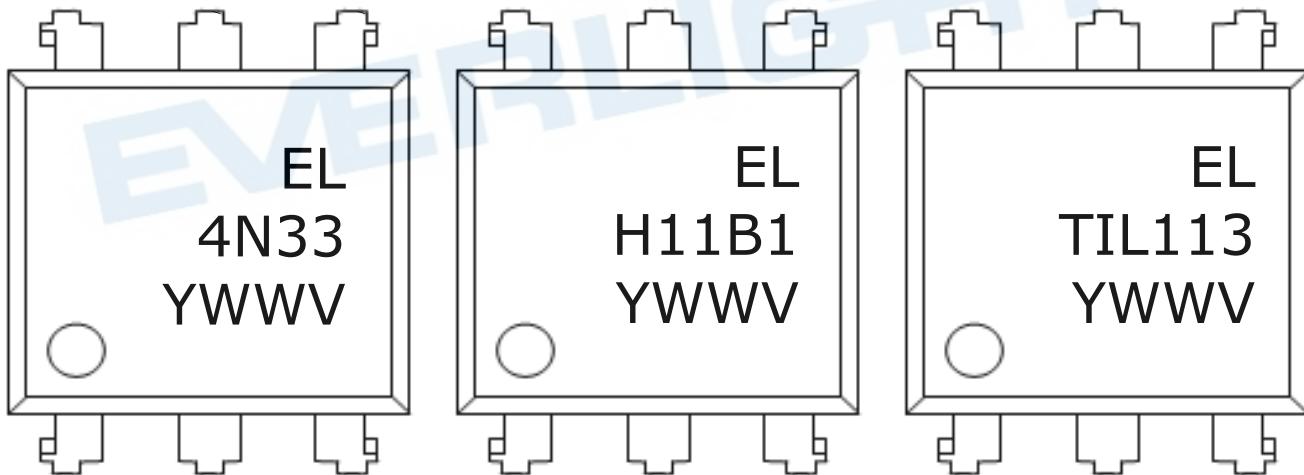
Recommended pad layout for surface mount leadform



Notes

Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.

Device Marking

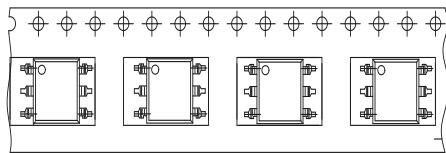


Notes

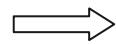
EL	denotes Everlight
4N33	
TIL113	
H11B1	denotes Part Number
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE safety (optional)

Tape & Reel Packing Specifications

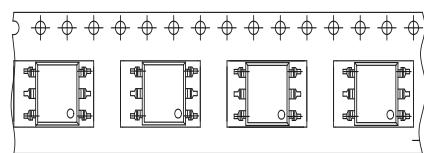
Option TA



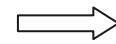
Direction of feed from reel



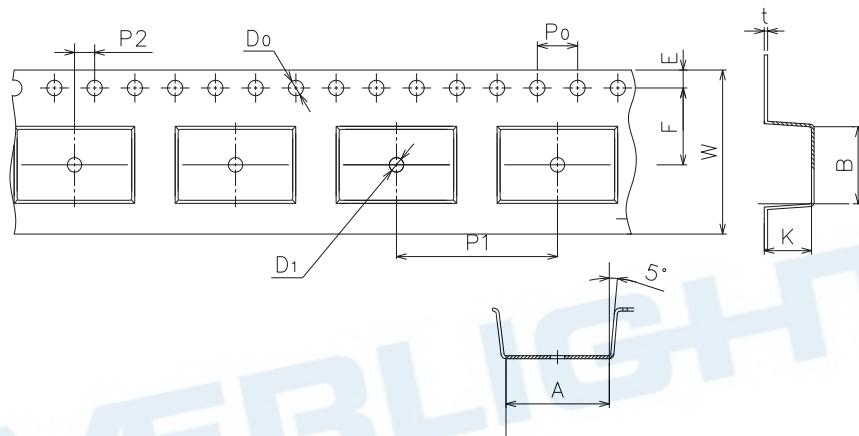
Option TB



Direction of feed from reel



Tape dimensions

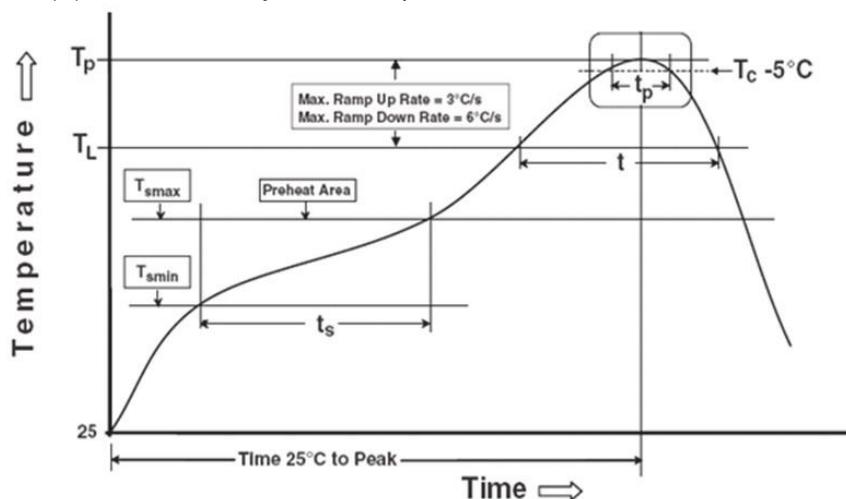


Dimension No.	A	B	Do	D1	E	F
Dimension(mm)	10.8 ± 0.1	7.55 ± 0.1	1.5 ± 0.1	$1.5 +0.1/-0$	1.75 ± 0.1	7.5 ± 0.1
Dimension No.	Po	P1	P2	t	W	K
Dimension(mm)	4.0 ± 0.15	12 ± 0.1	2.0 ± 0.1	0.35 ± 0.03	16.0 ± 0.2	4.5 ± 0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5°C$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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